



Docket No.: 2000P4162

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By:

Date: July 25, 2001

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Knut Kahlisch et al.
Applic. No. : 09/901,550
Filed : July 9, 2001
Title : Support Matrix with Bonding Channel for Integrated Semiconductors, and Method for Producing it

INFORMATION DISCLOSURE STATEMENT

Hon. Commissioner of Patents and Trademarks,
Washington, D.C. 20231

Sir:

In accordance with 37 C.F.R. 1.98 copies of the following patents and/or publications are submitted herewith:

U.S. Patent No. 5,866,949 (Schueller), dated February 2, 1999;

Japanese Patent Abstract JP 01217952 A (Masato), dated August 31, 1989;

Japanese Patent Abstract JP 10214924 A (Kazunori et al.), dated August 11, 1998;

European Application EP 0 472 766 A 1 (Franz et al.), dated March 4, 1992; method for covering a contacted semiconductor chip;

If no translation of pertinent portions of any foreign language patents or publications mentioned above is included with the aforementioned copies of those applications,

patents and/or publications, it is because no existing translation is readily available to the applicant.

Respectfully submitted,



For Applicants

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Date: July 25, 2001

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